

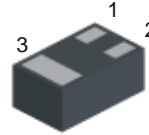
NEW PRODUCT

**Features**

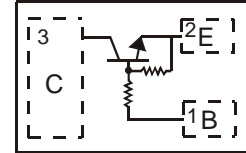
- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Lead Free By Design/RoHS Compliant (Note 1)**
- "Green" Device (Note 2)
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: DFN1006-3
- Case Material: Molded Plastic. "Green Molding" Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Collector Dot (See Diagram and Marking Information)
- Terminals: Finish - NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Code N4, Dot denotes Collector Side
- Ordering Information: See Page 3
- Weight: 0.0009 grams (approx.)

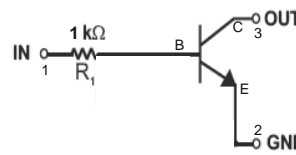


Bottom View

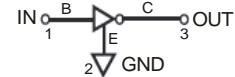


Top View

DFN1006-3



Schematic and Pin Configuration



Equivalent Inverter Circuit

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Supply Voltage	V <sub>CC</sub>	50	V
Input Voltage	V <sub>IN</sub>	-5 to +10	V
Output Current (I <sub>O</sub> )	I <sub>C(max)</sub>	100	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @T <sub>A</sub> = 25	P <sub>D</sub>	250	mW
Power Derating above 25°C	P <sub>der</sub>	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 3) @T <sub>A</sub> = 25 (Equivalent to one heated junction of NPN)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 4)</b>						
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	50	—	—	V	I <sub>C</sub> = 10μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	50	—	—	V	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	5	—	—	V	I <sub>E</sub> = 50μA, I <sub>C</sub> = 0
Collector-Base Cutoff Current	I <sub>CBO</sub>	—	—	0.5	μA	V <sub>CB</sub> = 50V, I <sub>E</sub> = 0
Emitter-Base Cutoff Current	I <sub>EBO</sub>	—	—	0.5	μA	V <sub>EB</sub> = 4V, I <sub>C</sub> = 0
<b>ON CHARACTERISTICS (Note 4)</b>						
DC Current Gain	h <sub>FE</sub>	100	380	600	—	V <sub>CE</sub> = 5V, I <sub>C</sub> = 1mA
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	—	0.25	V	I <sub>C</sub> = 50mA, I <sub>B</sub> = 2.5mA
Input Resistance	R <sub>1</sub>	0.7	1	1.3	KΩ	—
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Current Gain-Bandwidth Product	f <sub>T</sub>	—	250	—	MHz	V <sub>CE</sub> = 10V, I <sub>E</sub> = 5mA, f = 100MHz

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on page 3 or Diodes Inc. suggested pad layout document AP02001 on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  4. Short duration pulse test used to minimize self-heating effect.

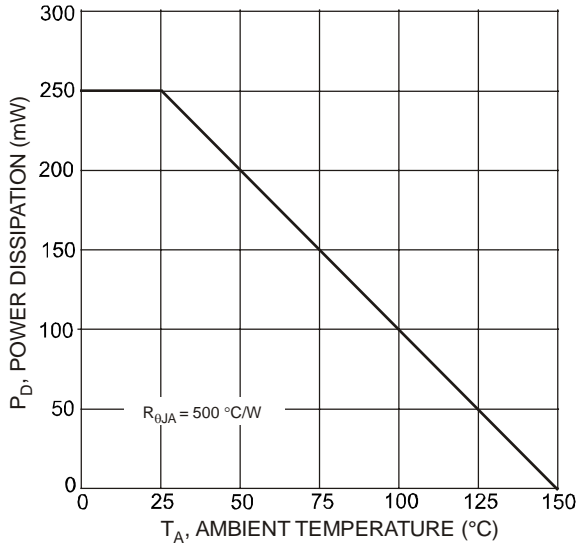


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

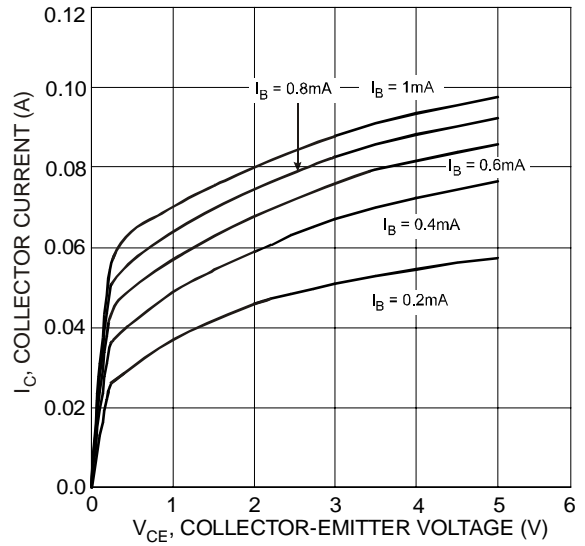


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage

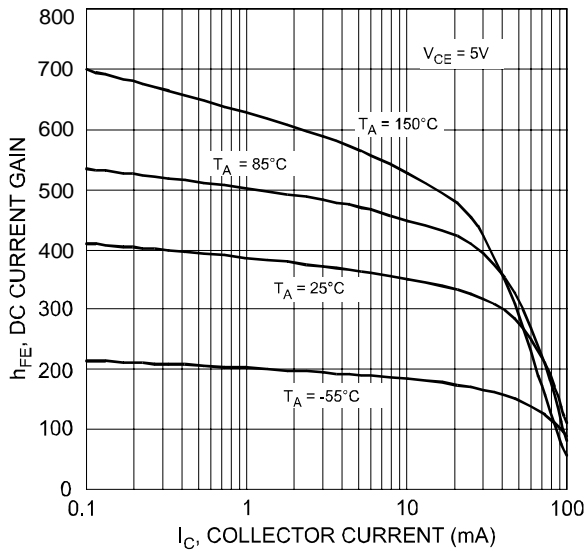


Fig. 3 Typical DC Current Gain vs. Collector Current

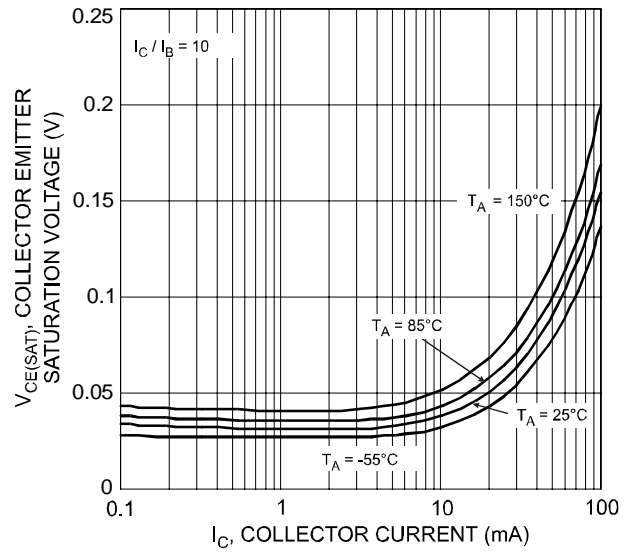


Fig. 4 Typical Collector Emitter Saturation Voltage vs. Collector Current

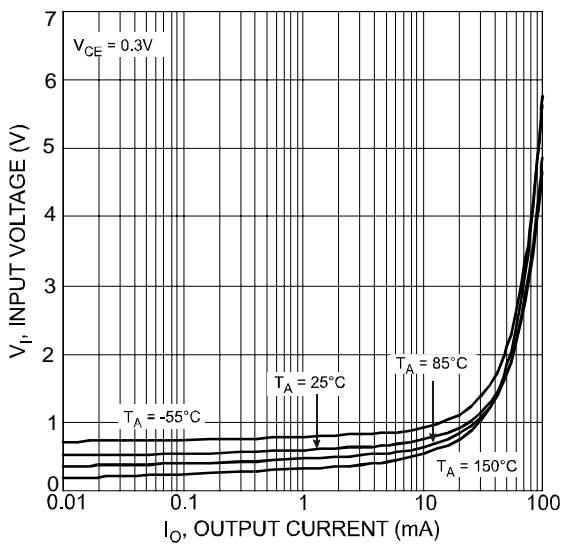


Fig. 5 Typical Input Voltage vs. Output Current (On Characteristics)

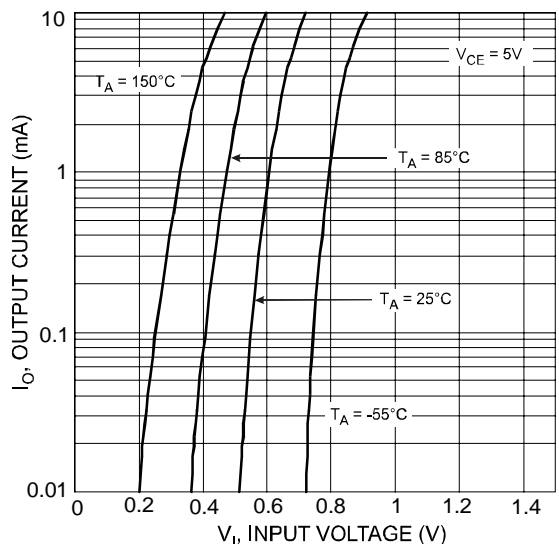


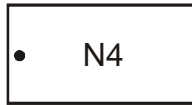
Fig. 6 Typical Output Current vs. Input Voltage (Off Characteristics)

## Ordering Information (Note 5)

Device	Packaging	Shipping
DDTC113TLP-7	DFN1006-3	3000/Tape & Reel

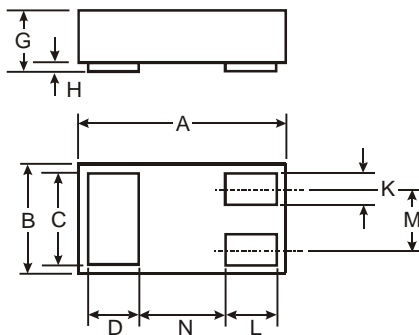
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



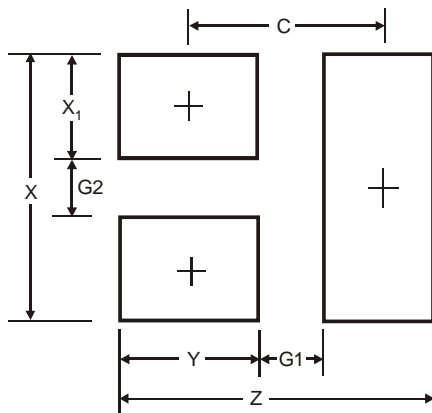
N4 = Product Type Marking Code  
Dot Denotes Collector, Pin 3

## Mechanical Details



DFN1006-3			
Dim	Min	Max	Typ
A	0.95	1.075	1.00
B	0.55	0.675	0.60
C	0.45	0.55	0.50
D	0.20	0.30	0.25
G	0.47	0.53	0.50
H	0	0.05	0.03
K	0.10	0.20	0.15
L	0.20	0.30	0.25
M	—	—	0.35
N	—	—	0.40
All Dimensions in mm			

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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